High Density Electronics Center

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HiDEC website (http://www.hidec.uark.edu/)

The High Density Electronics Center (HiDEC) was established in 1991 as an interdisciplinary research program in advanced electronic packaging technologies, particularly the rapidly developing technology of multichip modules (MCMs), which allow electronic systems to be small, fast, and cheap.

With generous support from the Defense Advanced Research Projects Agency (DARPA), a large clean room was constructed, and an MCM fabrication facility, unique among universities, was installed. Current research programs focus on 3-D electronic packaging, high density laminate substrates, co-fired ceramic substrates for wireless applications, high temperature superconducting (HTSC) tunable filters, micro electromechanical systems (MEMS), and integrated passives development. The program is located in the Department of Electrical Engineering but involves faculty from six departments and more than 25 graduate students. Continuing funding comes from DARPA and several industrial sponsors. Significant national recognition has resulted from work performed at HiDEC.

HiDEC also houses the Center of Excellence for Nano-, Micro-, and Neuro-Electronics, Sensors and Systems (CENNESS).